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- AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply Voltage
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Designed Specifically for High-Speed Memory Decoders and Data-Transmission Systems
- Incorporate Three Enable Inputs to Simplify Cascading and/or Data Reception
- Balanced Propagation Delays
- ±24-mA Output Drive Current
  Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

### description/ordering information

The 'AC138 decoders/demultiplexers are designed for high-performance memory-decoding and data-routing applications that require very short propagation-delay times. In high-performance memory systems, these decoders can be used to minimize the effects of system decoding. When employed with high-speed memories utilizing a fast enable circuit, the delay times of these decoders and the enable time of the memory usually are less than the typical access time of the memory. This means that the effective system delay introduced by the decoders is negligible.

The conditions at the binary-select inputs and the three enable inputs select one of eight output lines. Two active-low and one active-high enable inputs reduce the need for external gates or inverters when expanding. A 24-line decoder can be implemented without external inverters, and a 32-line decoder requires only one inverter. An enable input can be used as a data input for demultiplexing applications (see Application Information).

ТА	PACKAGE <sup>†</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – E	Tube	CD74AC138E	CD74AC138E
–55°C to 125°C	SOIC – M	Tube	CD74AC138M	AC138M
-55°C to 125°C	301C - M	Tape and reel	CD74AC138M96	ACTSON
	CDIP – F	Tube	CD54AC138F3A	CD54AC138F3A

#### **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



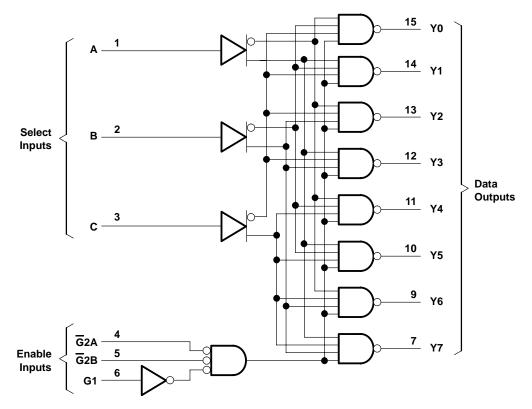
Copyright © 2003, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

CD54AC138 F PACKAGE CD74AC138 E OR M PACKAGE (TOP VIEW)										
A [	1	16	] V <sub>CC</sub>							
B [	2	15	] Y0							
C [	3	14	] Y1							
G2A [	4	13	] Y2							
G2B [	5	12	] Y3							
G1 [	6	11	] Y4							
Y7 [	7	10	] Y5							
GND [	8	9	] Y6							

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					F	UNCTIO	N TABL	E					
ENA	BLE INF	PUTS	SEL	ECT INF	UTS				OUT	PUTS			
G1	G2A	G2B	С	В	Α	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
Х	Н	Х	Х	Х	Х	н	Н	Н	Н	Н	Н	Н	Н
х	Х	н	Х	Х	Х	н	Н	Н	Н	Н	Н	Н	Н
L	х	х	Х	Х	Х	н	Н	Н	Н	Н	Н	Н	н
н	L	L	L	L	L	L	Н	Н	Н	Н	Н	Н	н
н	L	L	L	L	н	н	L	Н	Н	Н	Н	Н	н
н	L	L	L	Н	L	н	Н	L	Н	Н	Н	Н	н
н	L	L	L	Н	н	н	Н	Н	L	Н	Н	Н	н
н	L	L	н	L	L	н	Н	Н	Н	L	Н	Н	н
н	L	L	н	L	Н	н	Н	Н	Н	Н	L	Н	Н
н	L	L	н	Н	L	н	н	Н	Н	н	н	L	Н
н	L	L	Н	Н	Н	н	Н	Н	Н	Н	Н	Н	L

## logic diagram (positive logic)





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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	–0.5 V to 6 V
Input clamp current, I <sub>IK</sub> (VI < 0 V or VI > V <sub>CC</sub> ) (see Note 1)	
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 V or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 1)	±50 mA
Continuous output current, $I_O (V_O > 0 V \text{ or } V_O < V_{CC})$	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): E package	
M package	
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions (see Note 3)

			T <sub>A</sub> = 25°C		–55°( 125		–40°C to 85°C		UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX	ר	
VCC	Supply voltage		1.5	5.5	1.5	5.5	1.5	5.5	V	
		V <sub>CC</sub> = 1.5 V	1.2		1.2		1.2			
VIН	High-level input voltage	$V_{CC} = 3 V$	2.1		2.1		2.1		V	
		V <sub>CC</sub> = 5.5 V	3.85		3.85		3.85			
		V <sub>CC</sub> = 1.5 V		0.3		0.3		0.3		
VIL	Low-level input voltage	$V_{CC} = 3 V$		0.9		0.9		0.9	V	
		V <sub>CC</sub> = 5.5 V		1.65		1.65		1.65		
VI	Input voltage		0	VCC	0	VCC	0	VCC	V	
VO	Output voltage		0	VCC	0	VCC	0	VCC	V	
ЮН	High-level output current	V <sub>CC</sub> = 4.5 V to 5.5 V		-24		-24		-24	mA	
IOL	Low-level output current	V <sub>CC</sub> = 4.5 V to 5.5 V		24		24		24	mA	
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 1.5 V to 3 V		50		50		50	ns/V	
ΔυΔν	Input transition rise or fall rate	$V_{CC}$ = 3.6 V to 5.5 V		20		20		20	115/ V	

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Vcc	T <sub>A</sub> = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT	
				MIN	MAX	MIN	MAX	MIN	MAX		
			1.5 V	1.4		1.4		1.4			
		I <sub>OH</sub> = -50 μA	3 V	2.9		2.9		2.9			
V <sub>OH</sub> V <sub>I</sub> = V <sub>I</sub>			4.5 V	4.4		4.4		4.4			
	$V_I = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -4 \text{ mA}$	3 V	2.58		2.4		2.48		V	
		I <sub>OH</sub> = -24 mA	4.5 V	3.94		3.7		3.8			
		I <sub>OH</sub> = -50 mA†	5.5 V			3.85					
		I <sub>OH</sub> = -75 mA†	5.5 V					3.85			
			1.5 V		0.1		0.1		0.1		
		I <sub>OL</sub> = 50 μA	3 V		0.1		0.1		0.1		
			4.5 V		0.1		0.1		0.1		
VOL	$V_I = V_{IH} \text{ or } V_{IL}$	I <sub>OL</sub> = 12 mA	3 V		0.36		0.5		0.44	V	
		I <sub>OL</sub> = 24 mA	4.5 V		0.36		0.5		0.44		
		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				1.65		-		
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V						1.65		
Ц	$V_{I} = V_{CC} \text{ or } GND$		5.5 V		±0.1		±1		±1	μA	
ICC	$V_{I} = V_{CC} \text{ or GND},$	IO = 0	5.5 V		8		160		80	μA	
Ci					10		10		10	pF	

<sup>†</sup> Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.

# switching characteristics over recommended operating free-air temperature range, $V_{CC} = 1.5 \text{ V}$ , $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C to 125°C		–40°C to 85°C		UNIT	
		(001F01)	MIN M	IAX	MIN	MAX		
<sup>t</sup> PLH	A, B, C	Any Y		138		125	ns	
<sup>t</sup> PHL	А, В, С	Ally I		138		125	115	
<sup>t</sup> PLH	64	Any Y		138		125	ns	
<sup>t</sup> PHL	G1	Ally I		138		125	115	
<sup>t</sup> PLH	G2A, G2B	Any Y		125		114	ns	
<sup>t</sup> PHL	027, 020			125		114		



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# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	ТО (ОИТРИТ)	–55° 125		–40° 85°	UNIT	
			MIN	MAX	MIN	MAX	
<sup>t</sup> PLH		Any M	3.9	15.4	4	14	
<sup>t</sup> PHL	A, B, C	Any Y	3.9	15.4	4	14	ns
<sup>t</sup> PLH	01		3.9	15.4	4	14	
<sup>t</sup> PHL	G1	Any Y	3.9	15.4	4	14	ns
<sup>t</sup> PLH	G2A, G2B	Any X	3.5	14	3.6	12.7	-
<sup>t</sup> PHL	GZA, GZB	Any Y	3.5	14	3.6	12.7	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

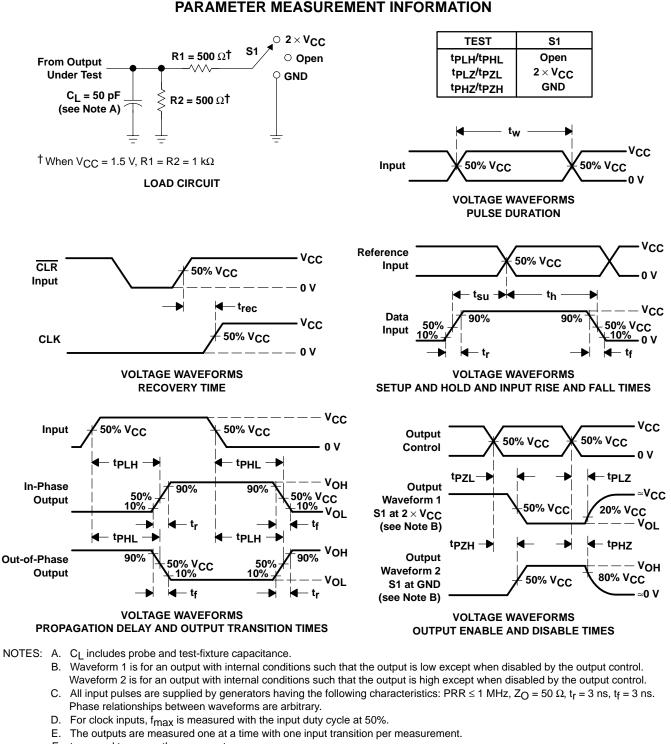
PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55° 125		–40° 85°	UNIT	
			MIN	MAX	MIN	MAX	
<sup>t</sup> PLH			2.8	11	2.8	10	
<sup>t</sup> PHL	A, B, C	Any Y	2.8	11	2.8	10	ns
<sup>t</sup> PLH		Any Y	2.8	11	2.8	10	ns
<sup>t</sup> PHL	G1		2.8	11	2.8	10	115
<sup>t</sup> PLH	G2A, G2B		2.5	10	2.6	9.1	200
<sup>t</sup> PHL	GZA, GZB	Any Y	2.5	10	2.6	9.1	ns

## operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = $25^{\circ}$ C

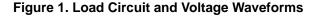
	PARAMETER				
C <sub>pd</sub>	Power dissipation capacitance	110	pF		



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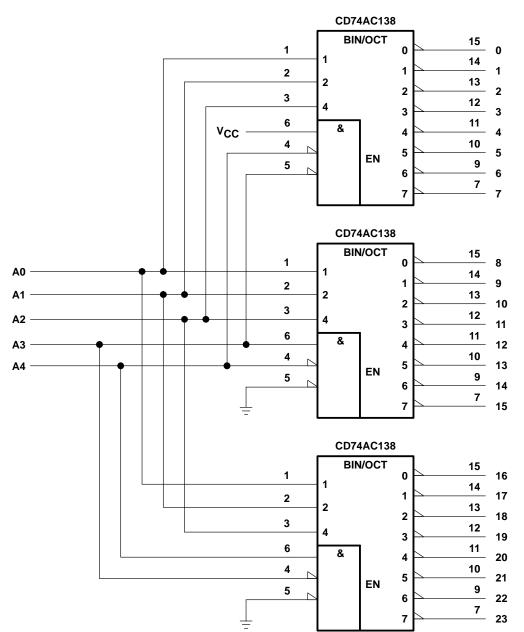


- F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- G. tPZL and tPZH are the same as ten.
- H.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- I. All parameters and waveforms are not applicable to all devices.





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**APPLICATION INFORMATION** 

Figure 2. 24-Bit Decoding Scheme



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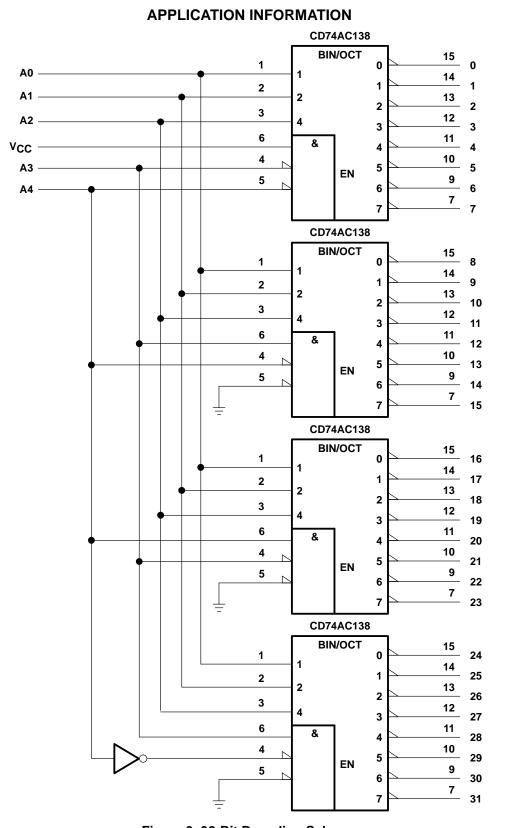


Figure 3. 32-Bit Decoding Scheme



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### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CD54AC138F3A	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD74AC138E	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74AC138EE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74AC138M	ACTIVE	SOIC	D	16	40	Green (RoHS 8 no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC138M96	ACTIVE	SOIC	D	16	2500	Green (RoHS 8 no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC138M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS 8 no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC138M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS 8 no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC138ME4	ACTIVE	SOIC	D	16	40	Green (RoHS 8 no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC138MG4	ACTIVE	SOIC	D	16	40	Green (RoHS 8 no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD**: The Pb-Free/Green conversion plan has not been defined.

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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## TAPE AND REEL INFORMATION





# QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC138M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74AC138M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1



# PACKAGE MATERIALS INFORMATION

19-Mar-2008



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC138M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74AC138M96	SOIC	D	16	2500	346.0	346.0	33.0

J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



D(R-PDSO-G16)



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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